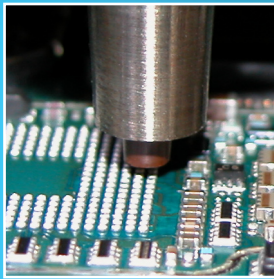
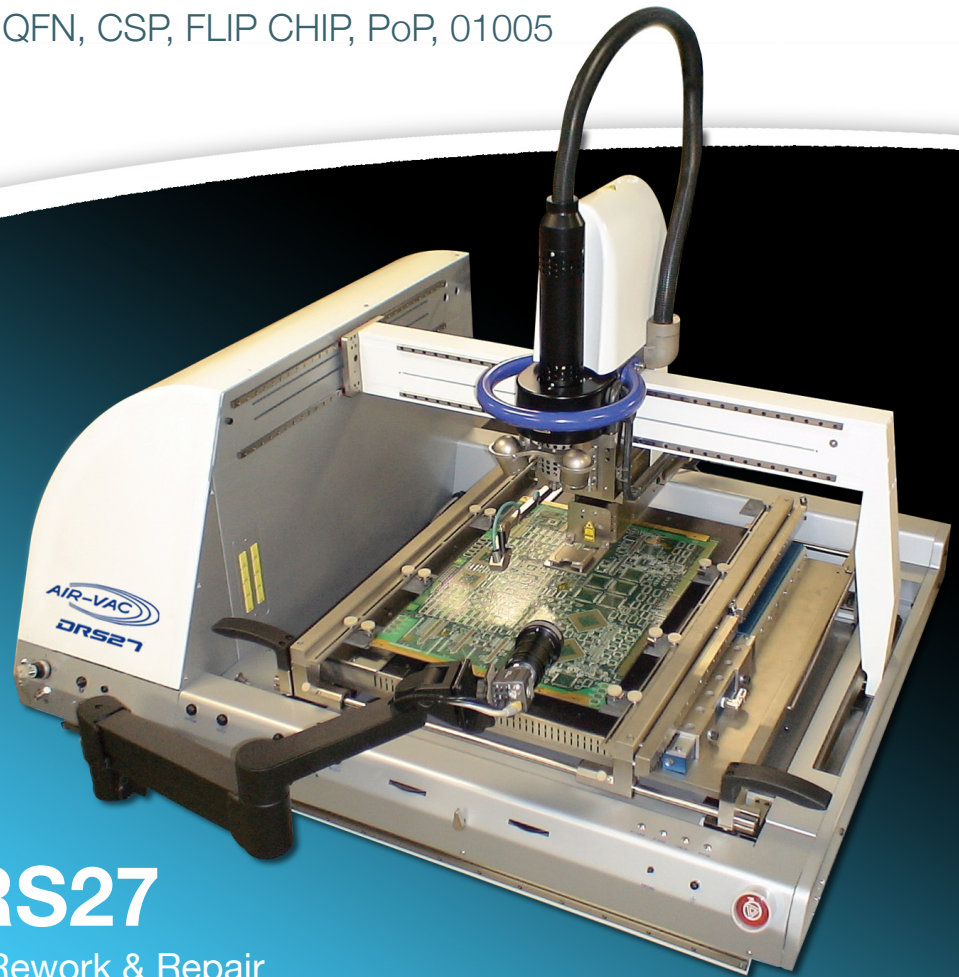


Large Board BGA/SMT Rework with 70 to 125mm Vision Alignment

BGA, QFN, CSP, FLIP CHIP, PoP, 01005



DRS27 SMT Rework & Repair

New Expandable Carrier

Flexible Bottom-Side Clearance

Carrier measures 18" or 32" wide X any depth.
Keep close for performance - away for up to 1.62" clearance.

High Efficiency IR Preheater

Excellent Thermal Uniformity

- Insulated heating elements for ultra-fast heat up (+/- 5°C).
- Black ceramic, high-emissivity coating dramatically increases radiant energy to produce the significantly higher preheat temperatures required for lead-free rework.
- Excellent for high thermal mass, military type assemblies (metal frames).
- 2, 3 or 6 zone preheaters (see models on back)

State-of-the-Art Vision System

High Magnification, High Resolution

Multiple field-of-view camera allows for extremely close-up viewing of all four corners plus center area of part/location for precision alignment (70mm/125mm).

Integrated Board Cooling System

Programmable Cool Down

Built into the carrier, upper cool air injection bypasses heating element and air flows directly into nozzle (component).

Powerful & Repeatable Upper Heater

Any Standard or Special Device/Material

Heat is restricted to the solder joints on large connectors to 01005 components.

Site Cleaning Nozzles

Standard & Micro Sizes

Completely remove residual site solder without damaging pads, or solder mask without disturbing adjacent components.

Consistent, Precision Vision Alignment

Moveable X/Y Head and Fixed Board Locations

Assemblies remain at a fixed position in the carrier while the overhead robotic head picks, aligns and places components with an 18 micron placement accuracy.

Automatic Component Pick and Place

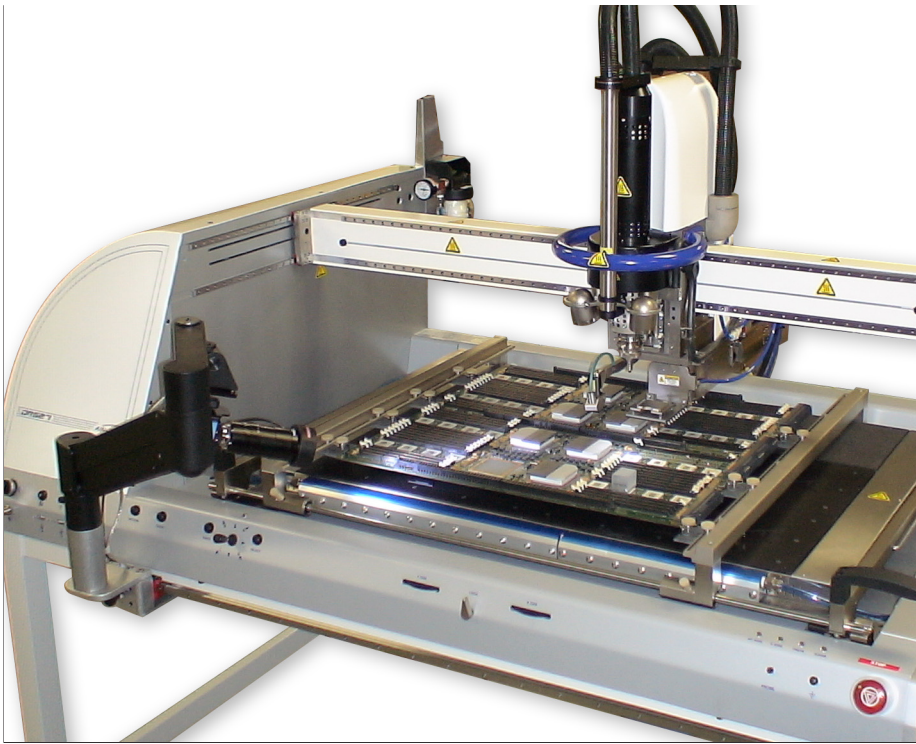
Motorized Z-Axis & Theta Rotation

Control motion with joystick. Programmable component pick-up and adjustable force placement (20-2000 grams).

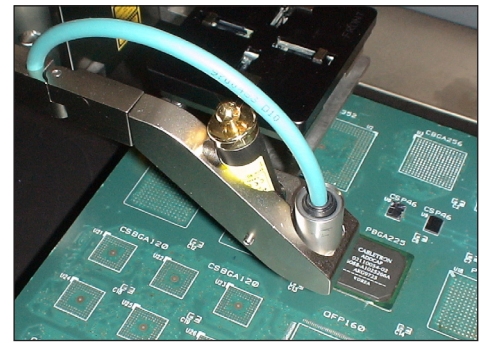
User-Friendly Thermal Tutor Software

On-The-Fly Adjustments

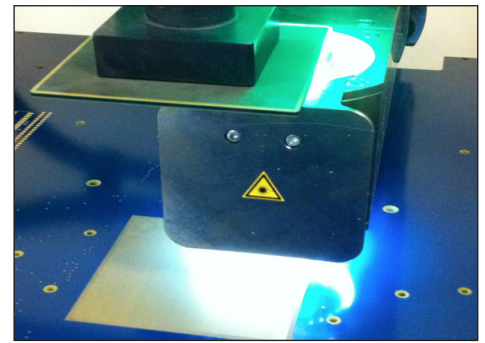
Profile library and master thermal templates are part of the software package.



DRS27T.6Z FOR HIGH MASS AND EXTRA LARGE ASSEMBLIES



PIVOTING IR SENSOR WITH LASER POINTER OPTION



125MM VISION SYSTEM OPTION

DRS27 Models:

DRS27T.3Z (standard)

- 3-zone, 16" x 24" IR preheater, 7,500 watts

DRS27T.6Z (extra large)

- 6-zone, 32" x 24" IR preheater, 15,000 watts

All Systems Include:

- **High Efficiency IR Preheater**
- **70mm Topside Clearance** - (max. component size)
- **Programmable Board Cooling System** - (Air-Knife)
- **2000 Watt Top Heater**
- **Cool-Air Injection** - (nozzle)
- **Motorized Z axis and Theta control**
- **Multiple Field of View Vision** - with top/bottom LED lighting, (x and y motor drives)
- **Joystick operation** - for all motor controls
- **8 Thermocouple Channels**
- **Welded Steel Frame with Side Table**
- **Adjustable LED Lighting for PCB**
- **Thermal Tutor Software**
- **DELL PC/ Flat Screen Monitor/Keyboard/Mouse**
- **Tool Kit & Board Supports**

DRS27 Specifications:

Dimensions:

- 67"W x 57"D x 72"H (DRS27T.2Z & DRS27T.3Z)
- 82"W x 57"D x 72"H (DRS27T.6Z)

Weight:

- 750 lbs., est. (DRS27T.2Z & DRS27T.3Z)
- 1,000 lbs., est. (DRS27T.6Z)

Recommended Options:

- **Pivoting IR Sensor w/Laser Pointer** - Process repeatability by insuring the board is at the exact same target temperature each time.
- **Site Cleaning System** - Standard and micro nozzles for complete solder removal.
- **Universal Insertion Tool** - Mechanically self-centers any device for accurate pick up.
- **Bottom Side Convection Spot Heater**
- **Direct View Camera** - High magnification site viewing.
- **125mm Vision Alignment** - 125mm max. component size.
- **Dipping Kit for Solder Paste or Flux** - Superior to applying paste via component or stencils.
- **14 Standard EZ Nozzles**